

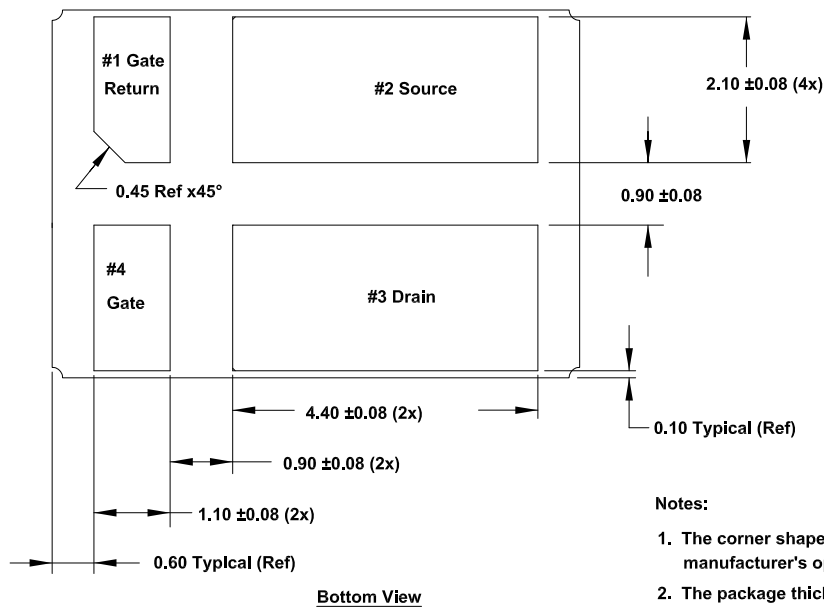
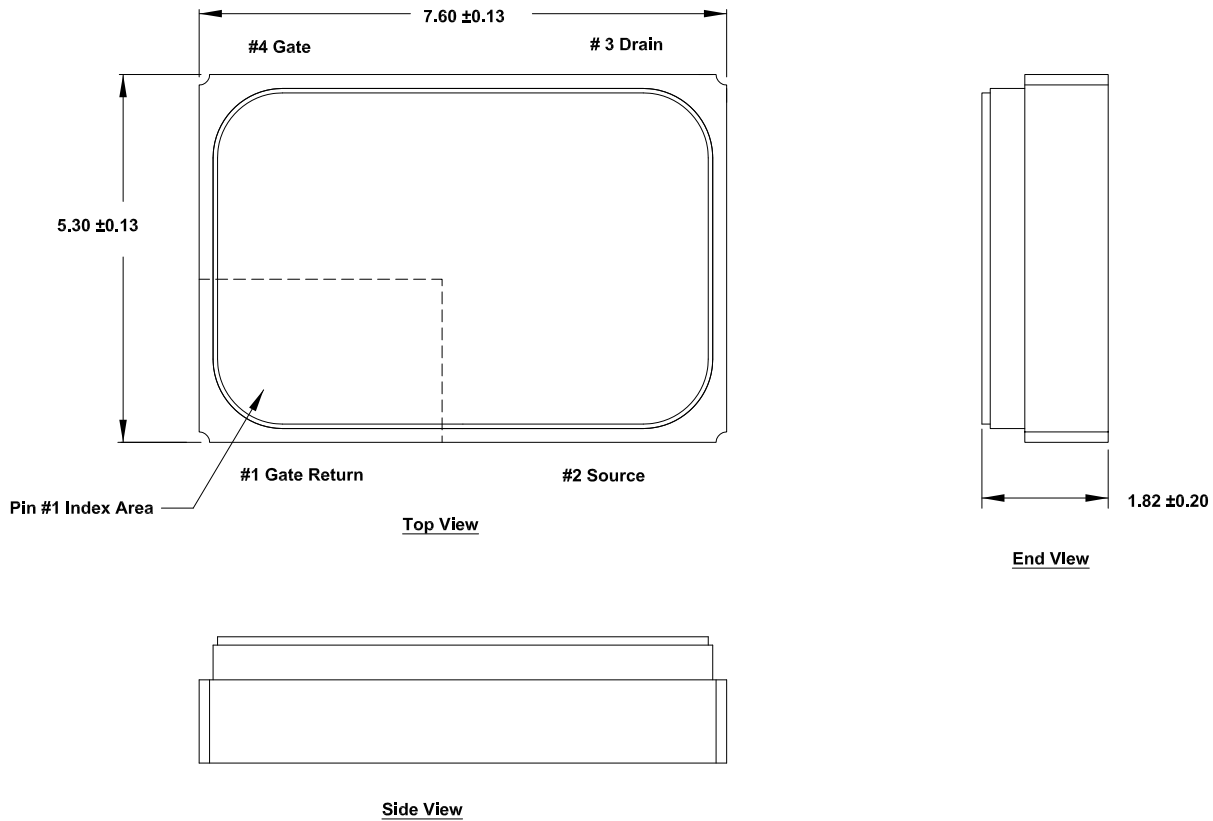
Hermetic Packages for Integrated Circuits

Package Outline Drawing

J4.B

4 Pin 5.3mmx7.6mm Hermetic Surface Mount Package

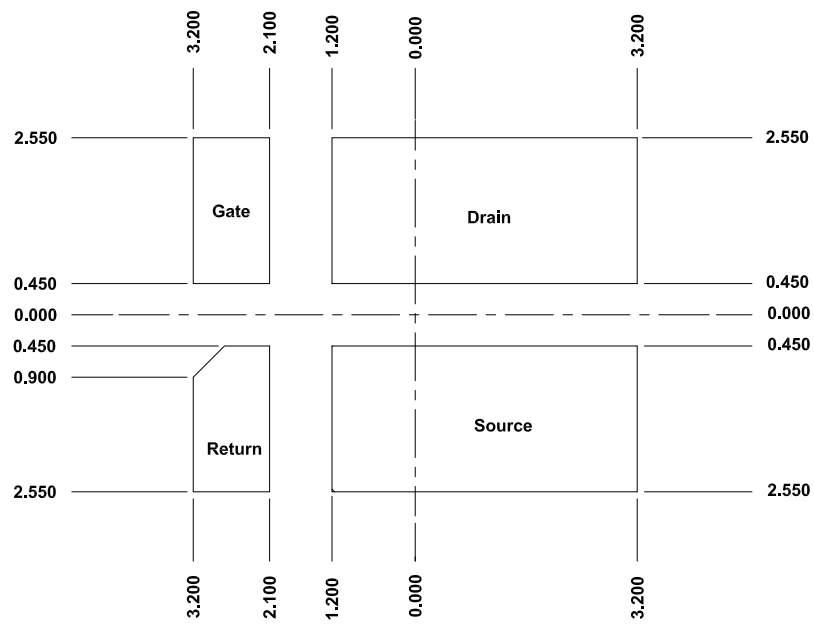
Rev 0, 9/20



Notes:

1. The corner shape (radius, chamfer, etc.) may vary at the manufacturer's option from that shown on the drawing.
2. The package thickness dimension is the package height before being solder dipped.
3. Dimensions are in mm.

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Typical Recommended Land Pattern